

Claim 1 (Previously Presented): A focus ring assembly configured to reduce process effects on the backside of a substrate that is cantilevered beyond an edge of a substrate holder support surface on which the substrate rests, the focus ring assembly comprising:

a focus ring positioned on a step receiving surface of the substrate holder which is axially recessed from the substrate holder support surface and extends radially outward from the edge of the substrate holder support surface, the focus ring comprising:

a bottom surface which contacts the step receiving surface of the substrate holder,

a top surface which opposes the bottom surface and is axially positioned at a higher level than the substrate support surface when the focus ring is positioned on the step receiving surface of the substrate holder, and also positioned at substantially a same planar level as a top surface of the substrate, and

a lip having a lip receiving surface axially located between the bottom surface and top surface of the focus ring, such that the lip receiving surface is located below a backside surface of a substrate resting on the substrate support surface of the substrate holder, and an outer radial lip surface positioned radially outward from a peripheral edge of the substrate and extending substantially perpendicularly upward from the lip receiving surface to the top surface of the focus ring such that the peripheral edge of said substrate is substantially parallel to the outer radial lip surface and a clearance space is formed between a cantilevered portion of the substrate and the lip of the focus ring; and

a secondary focus ring positioned on the lip receiving surface of the focus ring, the secondary focus ring including an outer radial edge surface extending axially

upward from the lip receiving surface and positioned radially outward from the peripheral edge of the substrate,

wherein said focus ring is configured to couple to the substrate holder which is configured to support the substrate exposed to a process in a processing system, and said secondary focus ring is configured to reduce deposition of material from said process on the backside surface of said substrate.

Claim 2 (Previously Presented): The focus ring assembly as recited in claim 1, wherein said secondary focus ring comprises a compliant material.

Claim 3 (Previously Presented): The focus ring assembly as recited in claim 2, wherein said compliant material comprises at least one of silicone rubber, polyimide, and Teflon.

Claim 4 (Previously Presented): The focus ring assembly as recited in claim 1, wherein said secondary focus ring comprises a rigid material.

Claim 5 (Previously Presented): The focus ring assembly as recited in claim 4, wherein said rigid material comprises at least one of a ceramic material, silicon, silicon carbide, silicon nitride, silicon dioxide, carbon, sapphire, and alumina.

Claim 6 (Previously Presented): The focus ring assembly as recited in claim 1, wherein said secondary focus ring comprises silicon having a resistivity less than or equal to 1 Ω -cm.

Claim 7 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the clearance space comprises an axial clearance space between the lip receiving surface of the focus ring and said backside surface on said substrate, and said secondary focus ring reduces said axial clearance space.

Claim 8 (Previously Presented): The focus ring assembly as recited in claim 7, wherein the clearance space comprises a radial clearance space between the peripheral edge of the substrate and the outer radial lip surface of the focus ring said secondary focus ring also reducing the radial clearance space.

Claim 9 (Previously Presented): The focus ring assembly as recited in claim 8, wherein said secondary focus ring eliminates said axial clearance space.

Claims 10-20. (Canceled).

Claim 21 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the outer radial lip surface of the focus ring is positioned radially outward from an outer radial edge surface of the secondary focus ring.

Claim 22 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the outer radial lip surface of the focus ring is positioned radially outward from and in contact with an outer radial edge surface of the secondary focus ring.

Claim 23 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the secondary focus ring has an annular shape and a cross-section of the secondary focus ring has a rectangular shape.

Claim 24 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the focus ring has an annular shape and a cross-section of the secondary focus ring has an L-shape.

Claim 25 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the secondary focus ring is positioned entirely radially outward from the substrate.

Claim 26 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the secondary focus ring includes an upper surface that is substantially planar with a top surface of the substrate.

Claim 27 (Cancelled)

Claim 28 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the entire secondary focus ring is positioned radially inside of the outer radial lip surface of the focus ring.

Claim 29 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the focus ring extends further radially inward than the secondary focus ring.

Claims 30-31 (Canceled).

Claim 32 (New): A focus ring assembly configured to reduce process effects on the backside of a substrate that is cantilevered beyond an edge of a substrate holder support surface on which the substrate rests, the focus ring assembly comprising:

a focus ring positioned on a step receiving surface of the substrate holder which is axially recessed from the substrate holder support surface and extends radially outward from the edge of the substrate holder support surface, the focus ring comprising:

a bottom surface which contacts the step receiving surface of the substrate holder,

a top surface which opposes the bottom surface, the focus ring being dimensioned such that the top surface is axially positioned at a higher level than the substrate support surface and also positioned at substantially a same planar level as a top surface of the substrate when the focus ring is positioned on the step receiving surface of the substrate holder, and the substrate is resting on the substrate holder support surface,

a lip having a lip receiving surface axially located between the bottom surface and top surface of the focus ring at a position such that the lip receiving surface is located below a backside surface of a substrate when the substrate is resting on the substrate support surface of the substrate holder,

and an outer radial lip surface positioned radially outward from a peripheral edge of the substrate when the substrate is resting on the substrate holder support surface and extending substantially perpendicularly upward from the lip receiving surface to the top surface of the focus ring at a position such that the peripheral edge of said substrate is substantially parallel to the outer radial lip surface and a clearance

space is formed between a cantilevered portion of the substrate and the lip of the focus ring; and

a secondary focus ring positioned on the lip receiving surface of the focus ring, the secondary focus ring including an outer radial edge surface extending axially upward from the lip receiving surface and positioned radially outward from the peripheral edge of the substrate when the substrate is resting on the substrate holder support surface,

wherein said focus ring is configured to couple to the substrate holder which is configured to support the substrate exposed to a process in a processing system, and said secondary focus ring is configured to reduce deposition of material from said process on the backside surface of said substrate.